

## Electronic Patent Application Fee Transmittal

Application Number:	10821432			
Filing Date:	09-Apr-2004			
Title of Invention:	High voltage semiconductor device utilizing a deep trench structure			
First Named Inventor:	Chen-Bau Wu			
Filer:	David M. Odell/Bonnie Boyle			
Attorney Docket Number:	24061.148(TSMC2003-0893)			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>120</b>